

ABSTRACT OF THE DISCLOSURE

A method is disclosed for one embodiment. An amount of photoresist is deposited upon a substrate, the amount of photoresist more than necessary to coat the substrate. The substrate is spun within a bowl such that an excess amount of photoresist is propelled off of the substrate to an interior surface of the bowl. A portion of the excess amount of photoresist is recovered and treated such that the recovered portion of the excess amount of photoresist is rendered usable.